

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V _{DSS}	-40	V
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Drain Current, V _{GS} = -10V	Steady State	T _A = +25°C (Note 6)	-6.4	A
		T _A = +70°C (Note 6)	-5.1	
		T _A = +25°C (Note 5)	-4.6	
Maximum Body Diode Forward Current (Note 6)		I _S	-5.2	A
Pulsed Drain Current (Note 7)		I _{DM}	-21	A
Pulsed Source Current (Note 7)		I _{SM}	-21	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

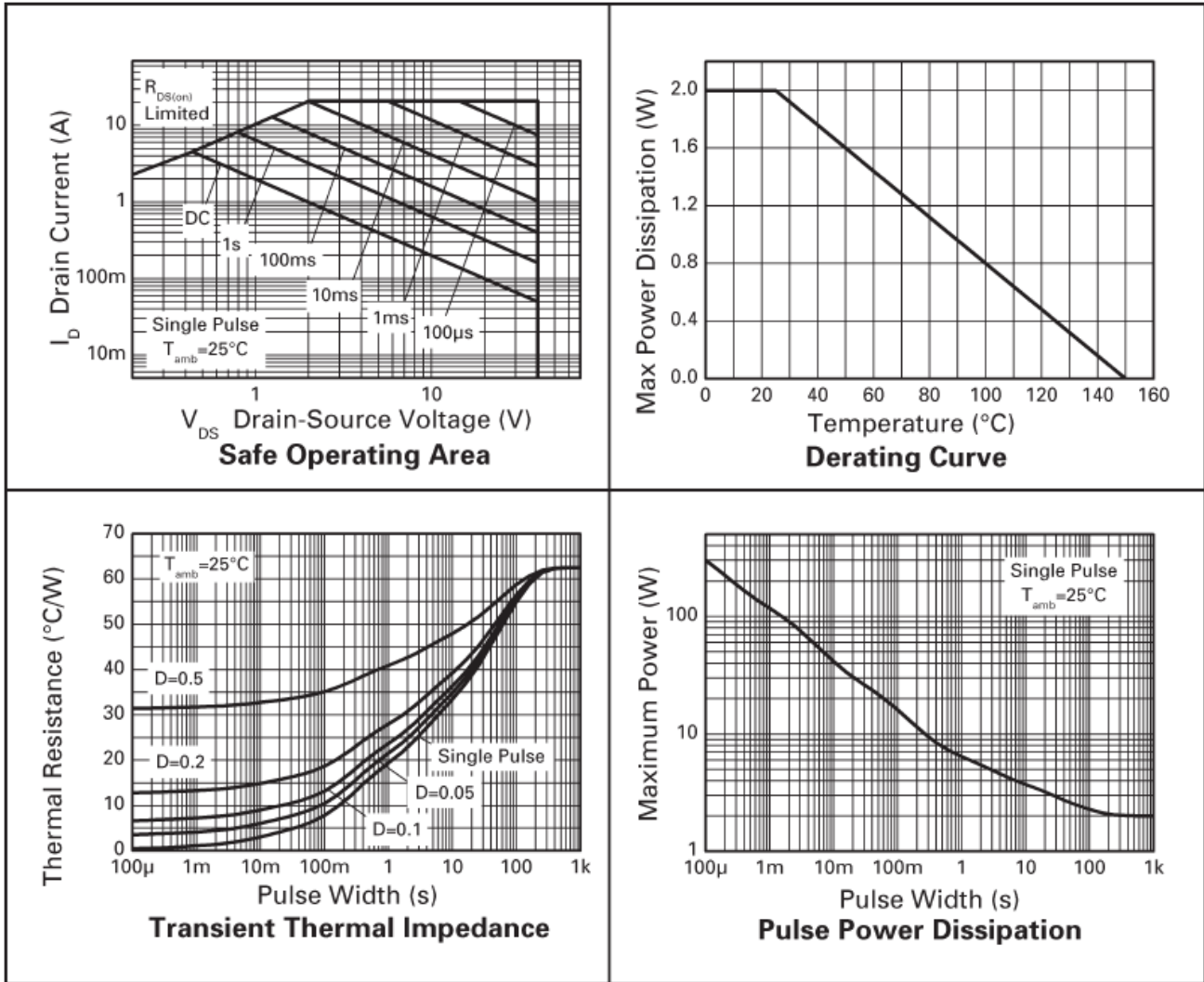
Characteristic		Symbol	Value	Units
Total Power Dissipation	T _A = +25°C (Note 5)	P _D	2.0	W
Linear Derating Factor			16	mW/°C
Total Power Dissipation	T _A = +25°C (Note 6)	P _D	3.9	W
Linear Derating Factor			31	mW/°C
Thermal Resistance, Junction to Ambient	Steady state (Note 5)	R _{θJA}	62.5	°C/W
	Steady state (Note 6)		32	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

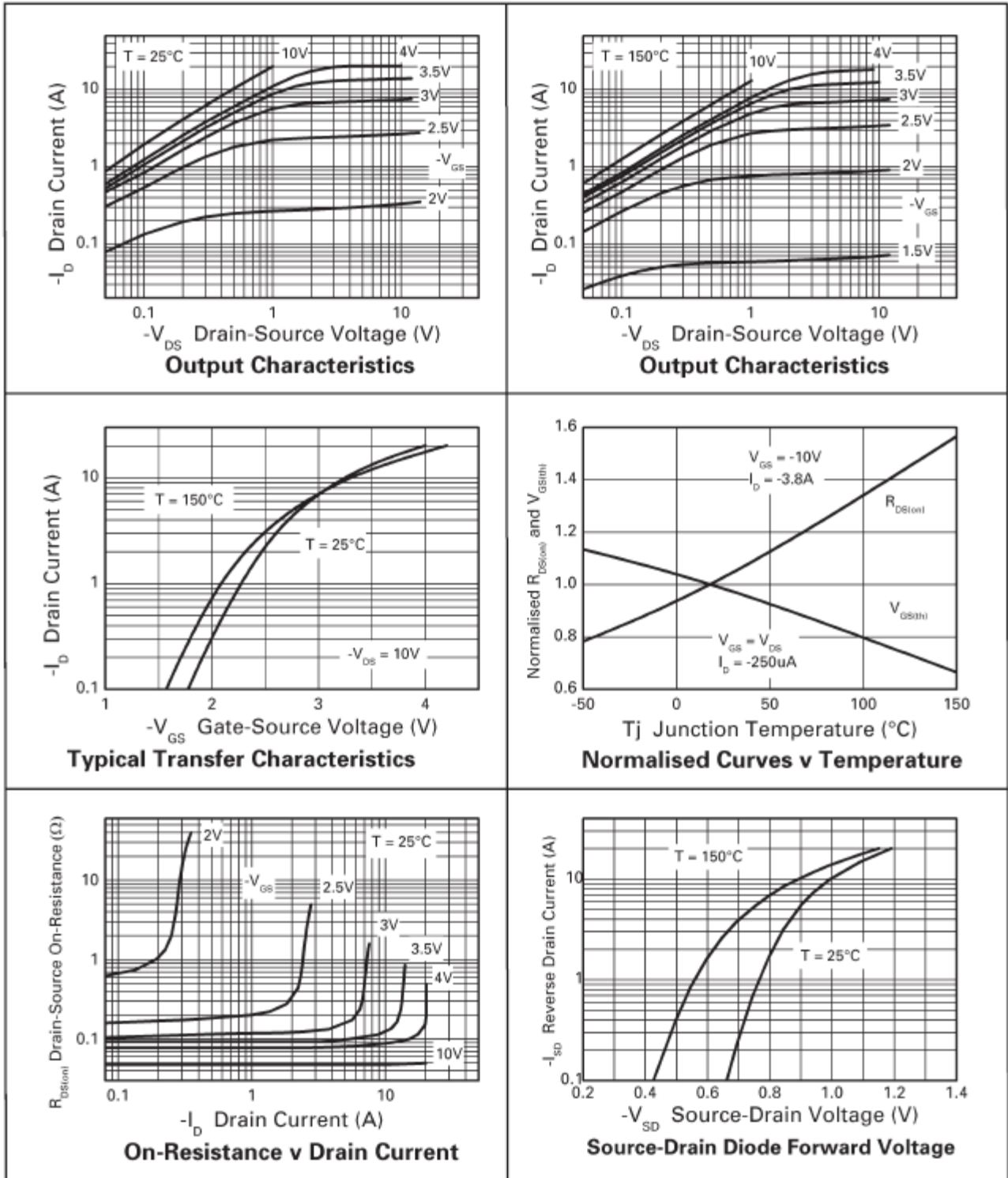
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV _{DSS}	-40	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1.0	μA	V _{DS} = -40V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V _{GS(th)}	-1.0	—	—	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance (Note 8)	R _{DS(ON)}	—	—	60	mΩ	V _{GS} = -10V, I _D = -3.8A
		—	—	100		V _{GS} = -4.5V, I _D = -2.9A
Diode Forward Voltage (Note 8)	V _{SD}	—	-0.85	-1.2	V	V _{GS} = 0V, I _S = -3.4A
Forward Transconductance (Notes 8 & 10)	g _{fs}	—	8.85	—	S	V _{DS} = -15V, I _D = -3.8A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C _{ISS}	—	1,007	—	pF	V _{DS} = -20V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{OSS}	—	130	—		
Reverse Transfer Capacitance	C _{RSS}	—	85	—		
Total Gate Charge (V _{GS} = -5.0V)	Q _g	—	13.6	—	nC	V _{DS} = -20V, I _D = -3.8A,
Total Gate Charge (V _{GS} = -10V)	Q _g	—	26.1	—		
Gate-Source Charge	Q _{gs}	—	2.8	—		
Gate-Drain Charge	Q _{gd}	—	4.8	—		
Turn-On Delay Time	t _{D(on)}	—	2.33	—	nS	V _{GS} = -10V, V _{DD} = -20V, R _G = 6.0Ω, I _D = -1.0A
Turn-On Rise Time	t _r	—	8.84	—		
Turn-Off Delay Time	t _{D(off)}	—	29.18	—		
Turn-Off Fall Time	t _f	—	12.54	—		
Body Diode Reverse Recovery Time	t _{rr}	—	27.2	—	nS	I _F = -3A, dI/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{rr}	—	25.4	—	nC	

- Notes:
5. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 6. For a device surface mounted on FR4 PCB measured at t ≤ 10 secs.
 7. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.05, pulse width limited by maximum junction temperature.
 8. Measured under pulsed conditions. Width ≤ 300μs. Duty cycle ≤ 2%.
 9. Short duration pulse test used to minimize self-heating effect.
 10. Guaranteed by design. Not subject to product testing.

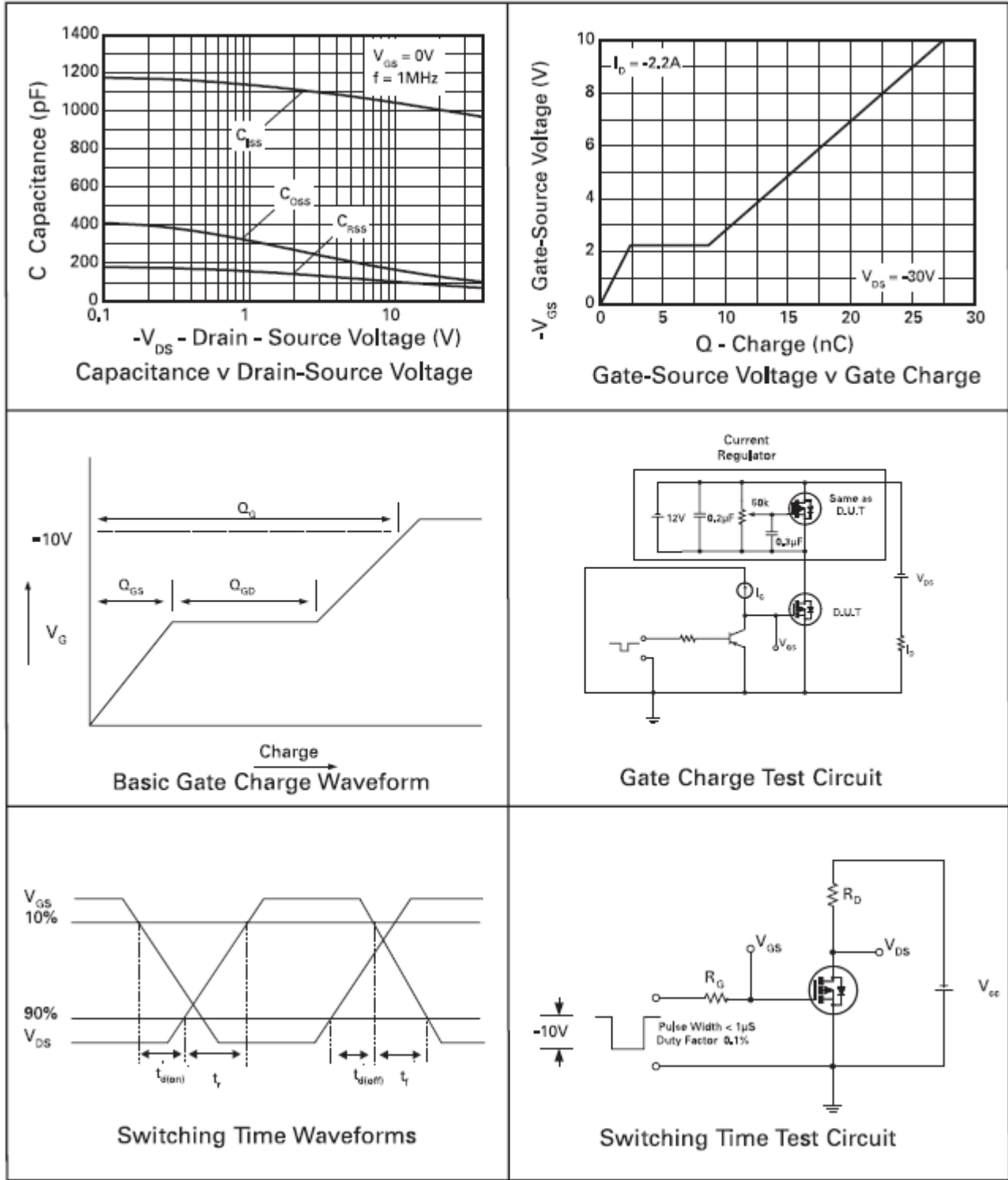
Typical Characteristics



Typical Characteristics (continued)

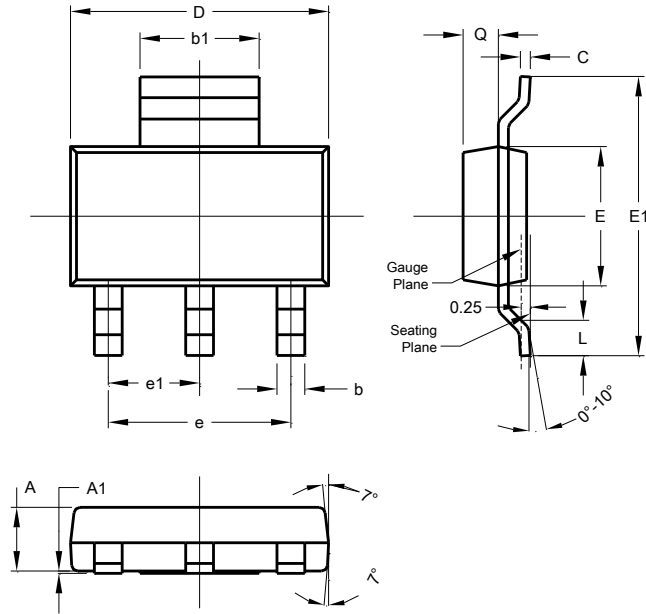


Typical Characteristics (continued)



Package Outline Dimensions

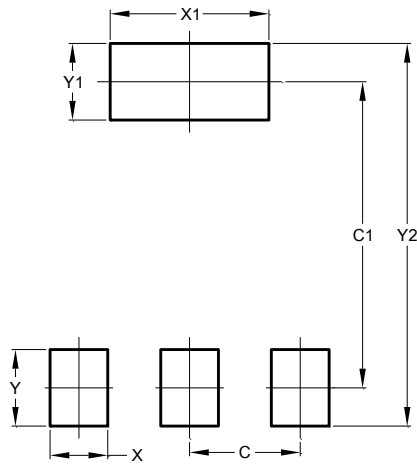
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

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